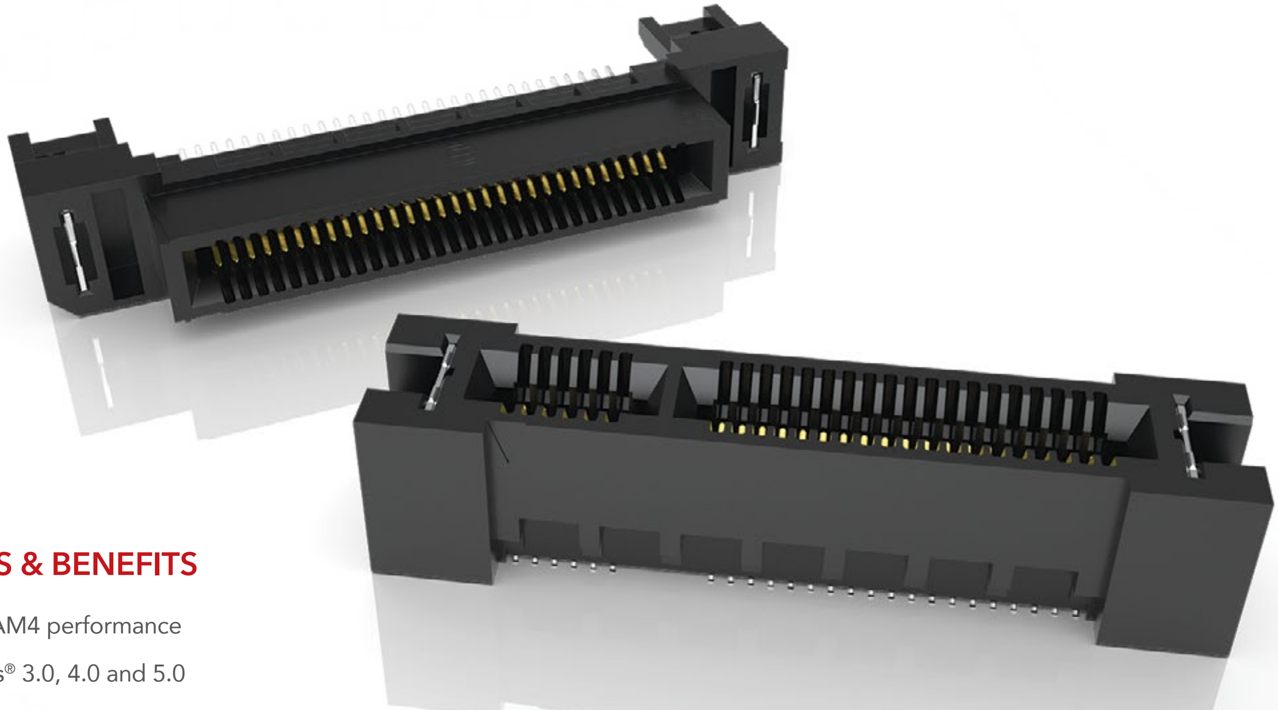
HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH

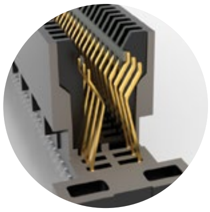


FEATURES & BENEFITS

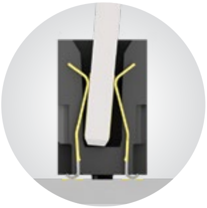
- 56 Gbps PAM4 performance
- PCI Express® 3.0, 4.0 and 5.0
- Edge Rate® contacts optimized for signal integrity performance and cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

PAM4 56 Gbps

EDGE® RATE CONTACT


Rugged tucked beam technology (HTEC8)


Differential pair for increased speed (HSEC8-DP)


Custom designs allow for misalignment in the X-Y axes (HSEC1)

KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	0.8 A (12 pins)	300 VAC	Yes
HTEC8	0.80 mm	40-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes

EDGE RATE® CONTACT

NRZ
28
Gbps

(0.80 mm) .0315" PITCH • RIGHT-ANGLE & EDGE MOUNT SOCKET

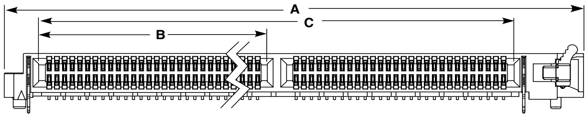
HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	RA	OTHER OPTIONS	"X"R
		09, 10, 13, 20, 25, 30, 40, 49, 50, 60	**–01** = (1.60 mm) .062" thick card	**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on tail **–S** = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on tail		**–BL** = Board Locks (09, 13, 25, 40, 49, 50, 60 only) **–L2** = ECDP Latching (09, 13, 25, 49 only)	Leave blank for Tray Packaging **–TR** = Tape & Reel **–FR** = Full Reel Tape & Reel Packaging (must order max. quantity per reel; contact Samtec for quantity breaks)

HSEC8-RA

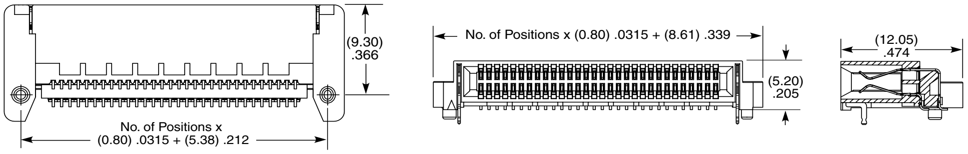
Card Mates:
(1.60 mm) .062" thick card, HSC8

Cable Mates:
ECDP

POSITIONS PER ROW	A	B	C
40	(43.80) 1.724	(18.90) .744	(36.60) 1.441
50	(51.80) 2.039	(22.90) .902	(44.60) 1.756
60	(59.80) 2.354	(26.90) 1.059	(52.60) 2.071
40-BL	(51.30) 2.020	(18.90) .744	(36.60) 1.441
50-BL	(59.30) 2.335	(22.90) .902	(44.60) 1.756
60-BL	(67.30) 2.650	(26.90) 1.059	(52.60) 2.071



40, 50, & 60 POSITIONS **-BL OPTION**



10, 20 & 30 POSITIONS

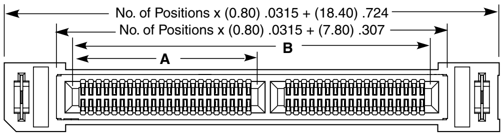
View complete specifications at: **samtec.com?HSEC8-RA**

HSEC8	1	POSITIONS PER ROW	01	PLATING OPTION	D	EM2
		10, 20, 30, 40, 50, 60		**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on tail **–S** = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on tail		**–EM2** =(1.60 mm) .062" thick PCB

HSEC8-EM

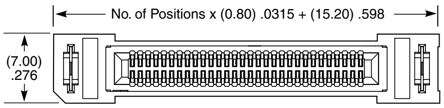
Card Mates:
(1.60 mm) .062" thick card, HSC8

Cable Mates:
ECDP

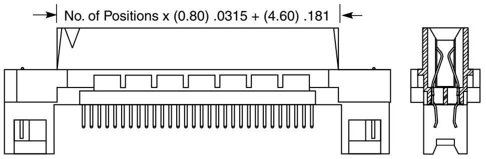


40, 50 & 60 POSITIONS

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071



10, 20 & 30 POSITIONS



Note:
Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: **samtec.com?HSEC8-EM**